Customer Information Notification

201412005I

Issue Date: 20-Dec-2014
Effective Date: 20-Mar-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
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QUALITY

Change Category

[ ] Wafer Fab process   [ ] Assembly Process   [ ] Product Marking   [ ] Design
[ ] Wafer Fab materials   [ ] Assembly Materials   [X] Electrical spec./Test coverage [ ] Mechanical Specification
[ ] Wafer Fab location   [ ] Assembly Location   [ ] Test Location   [ ] Packing/Shipping/Labeling

Datasheet update for ssMOS Product BSS138AKA

Information Notification

The datasheet for the BSS138AKA will be updated. The x-axis scale of graph Fig.14 will be changed from 0.4nC to 0.8nC. The product remains unchanged. There is no change of electrical and thermal specification limits.

Why do we issue this Information Notification
Editorial correction of previous data sheet.
Identification of Affected Products
Product identification does not change

Impact

no impact to the product's functionality anticipated.
Data Sheet Revision
A new datasheet will be issued

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name   GA Customer Support
e-mail address   DiscrQA.Helpdesk.GA-Products@nxp.com
At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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